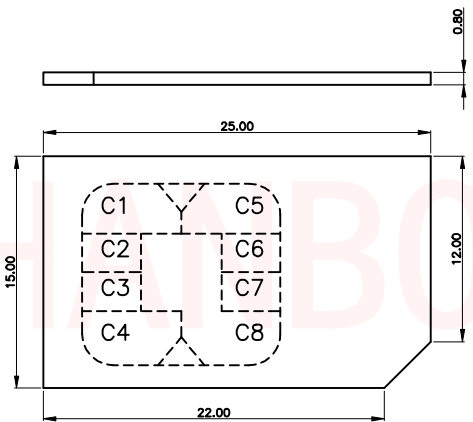
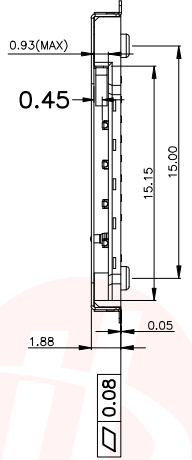
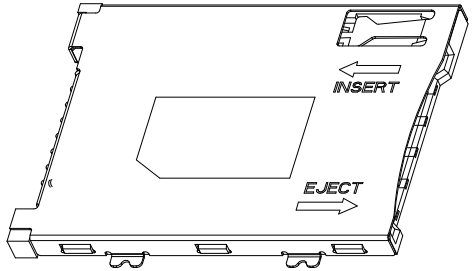
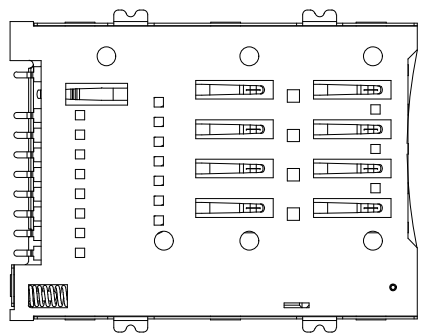
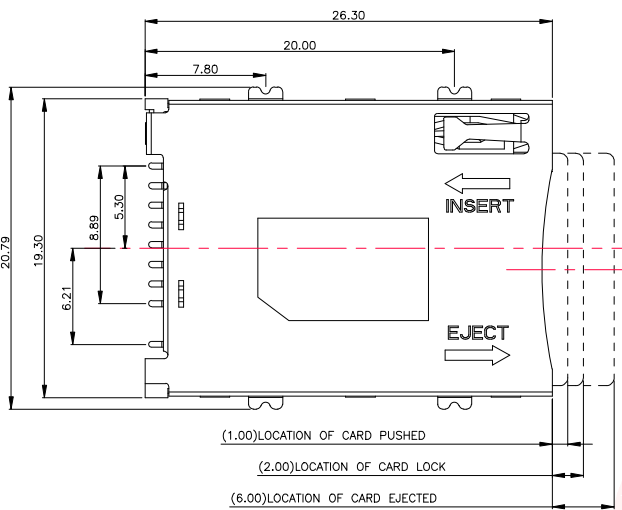


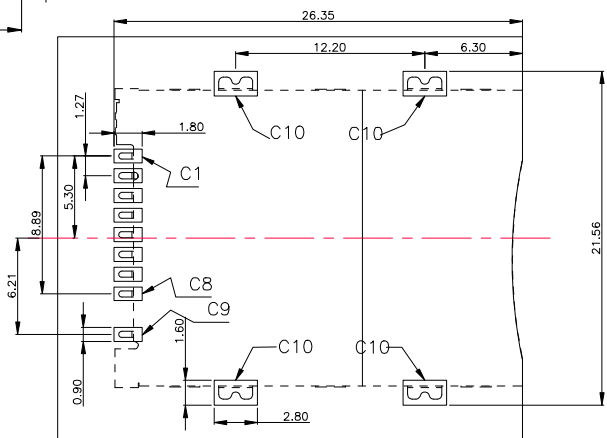
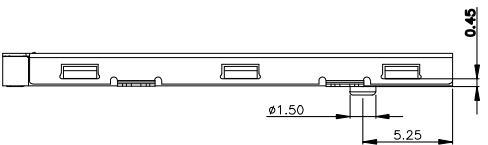


REV.	ECN NO OR DESCRIPTION	REVISED	DATE

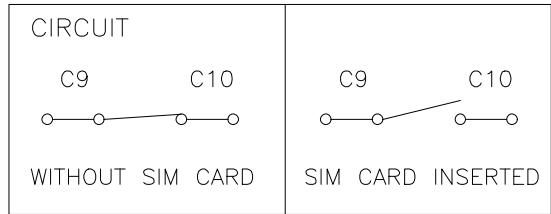


**NOTES:**

- MATERIAL:**  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V\_0, COLOR:BLACK.  
CONTACT: COPPER ALLOYS.  
COVER: COPPER ALLOYS OR STEEL.
- PLATING:**  
UNDERPLATE: NICKEL.  
CONTACT AREA: GOLD OVER NICKEL.  
SOLDER AREA: TIN OVER NICKEL.
- MULTIMEDIA CARD COMPATIBLE**



MINI SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	GND OF SIM
C3	RST OF SIM
C4	VPP OF SIM
C5	CLK OF SIM
C6	I/O OF SIM
C7	DATO OF SIM
C8	MCMD OF SIM
C9	CARD DETECT SWITCH
C10	GND OF SIM



RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS:	ANGLES:	TITLE	MINI SIM CARD PUSH PUSH 8+1PIN SMT无#1.9H
X :±0.35	X :±2°	DWN	xiong SIM-214
X.X :±0.25	X.X :±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX :±0.15		APVD	wang SIZE: A4 SHEET:1OF 1
		REV: A4	
CUSTOMER COPY			